

## Introduction

This chapter provides package information for HardCopy® III devices.

## Device and Package Information

HardCopy III device and package reference information is listed in [Table 12–1](#).

**Table 12–1. HardCopy III Devices in FBGA Packages Reference**

| Device | Package                  | Pins |
|--------|--------------------------|------|
| HC325W | FineLine BGA - Wire Bond | 484  |
|        |                          | 780  |
| HC325F | FineLine BGA - Flip Chip | 484  |
|        |                          | 780  |
| HC335L | FineLine BGA - Flip Chip | 1152 |
|        |                          | 1517 |
| HC335F | FineLine BGA - Flip Chip | 1152 |
|        |                          | 1517 |



For thermal resistance specifications and device package outlines for HardCopy III devices, refer to the [Altera Device Package Information Data Sheet](#).

## Document Revision History

[Table 12–2](#) shows the revision history for this document.

**Table 12–2. Document Revision History**

| Date          | Version | Changes   |
|---------------|---------|---|
| January 2011  | 3.1     | <ul style="list-style-type: none"> <li>■ Updated <a href="#">Table 12–1</a>: removed device HC315W.</li> <li>■ Used new document template.</li> </ul> |
| June 2009     | 3.0     | <ul style="list-style-type: none"> <li>■ Added non-socket replacement packaging information.</li> <li>■ Updated the new part numbers.</li> </ul>      |
| December 2008 | 2.0     | Made minor editorial changes.   |
| May 2008      | 1.0     | Initial release.  |

